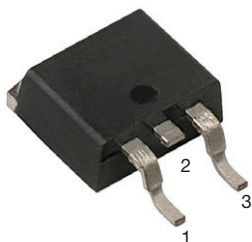
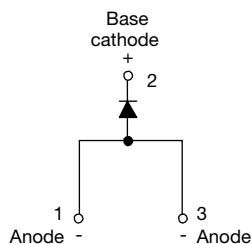


Surface Mount Fast Soft Recovery Rectifier Diode, 10 A


D²PAK (TO-263AB)


FEATURES

- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Glass passivated pellet chip junction
- AEC-Q101 qualified
- Meets JESD 201 class 1A whisker test
- Flexible solution for reliable AC power rectification
- High surge, low V_F rugged blocking diode for DC charging stations
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Input rectification
- On-board and off-board EV / HEV battery chargers

DESCRIPTION

The VS-10ETF12SLHM3 fast soft recovery rectifier series has been optimized for combined short reverse recovery time and low forward voltage drop.

The glass passivation ensures stable reliable operation in the most severe temperature and power cycling conditions.

PRIMARY CHARACTERISTICS

$I_{F(AV)}$	10 A
V_R	1200 V
V_F at I_F	1.33 V
I_{FSM}	155 A
t_{rr}	80 ns
T_J max.	150 °C
Package	D ² PAK (TO-263AB)
Circuit configuration	Single
Snap factor	0.6

MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	VALUES	UNITS
$I_{F(AV)}$	Sinusoidal waveform	10	A
V_{RRM}		1200	V
I_{FSM}		155	A
V_F	10 A, $T_J = 25$ °C	1.33	V
t_{rr}	1 A, 100 A/μs	80	ns
T_J	Range	-40 to +150	°C

VOLTAGE RATINGS

PART NUMBER	V_{RRM} , MAXIMUM PEAK REVERSE VOLTAGE V	V_{RSM} , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I_{RRM} AT 150 °C mA
VS-10ETF12SLHM3	1200	1300	4

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum average forward current	$I_{F(AV)}$	$T_C = 125$ °C, 180° conduction half sine wave	10	A
Maximum peak one cycle non-repetitive surge current	I_{FSM}	10 ms sine pulse, rated V_{RRM} applied	130	
		10 ms sine pulse, no voltage reapplied	155	
Maximum I^2t for fusing	I^2t	10 ms sine pulse, rated V_{RRM} applied	85	A ² s
		10 ms sine pulse, no voltage reapplied	120	
Maximum $I^2\sqrt{t}$ for fusing	$I^2\sqrt{t}$	$t = 0.1$ ms to 10 ms, no voltage reapplied	1200	A ² √s

**ELECTRICAL SPECIFICATIONS**

PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum forward voltage drop	V_{FM}	10 A, $T_J = 25\text{ }^{\circ}\text{C}$		1.33	V
Forward slope resistance	r_t	$T_J = 150\text{ }^{\circ}\text{C}$		22.9	$\text{m}\Omega$
Threshold voltage	$V_{F(TO)}$			0.96	V
Maximum reverse leakage current	I_{RM}	$T_J = 25\text{ }^{\circ}\text{C}$	$V_R = \text{rated } V_{RRM}$	0.1	mA
		$T_J = 150\text{ }^{\circ}\text{C}$		4	

RECOVERY CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Reverse recovery time	t_{rr}	I_F at 10 A _{pk} 25 A/ μs 25 $^{\circ}\text{C}$	310	ns	
Reverse recovery current	I_{rr}		4.7	A	
Reverse recovery charge	Q_{rr}		1.05	μC	
Typical snap factor	S		0.6		

THERMAL - MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}		-40 to +150	$^{\circ}\text{C}$
Maximum thermal resistance, junction to case	R_{thJC}	DC operation	1.5	$^{\circ}\text{C/W}$
Maximum thermal resistance, junction to ambient (PCB mount)	$R_{thJA}^{(1)}$		62	
Approximate weight			2	g
			0.07	oz.
Marking device		Case style D ² PAK (TO-263AB)	10ETF12SH	

Note

⁽¹⁾ When mounted on 1" square (650 mm²) PCB of FR-4 or G-10 material 4 oz. (140 μm) copper 40 $^{\circ}\text{C/W}$

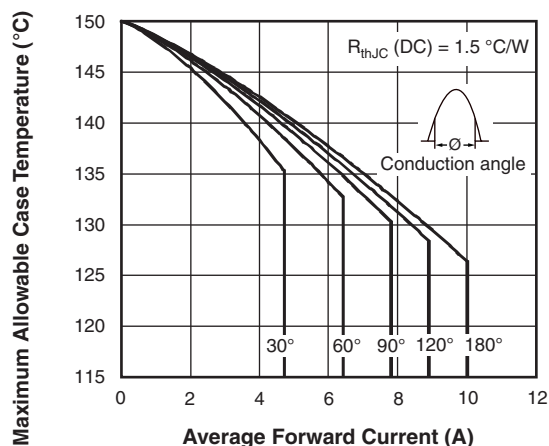


Fig. 1 - Current Rating Characteristics

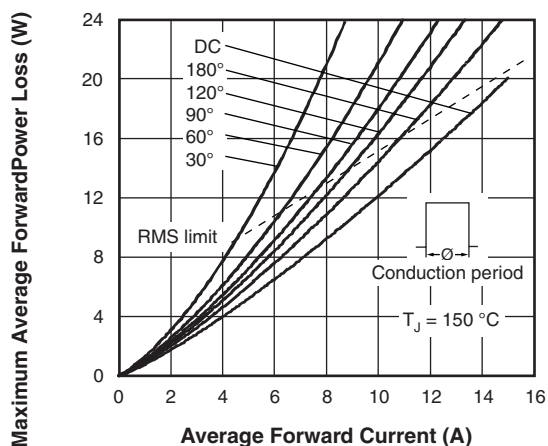


Fig. 4 - Forward Power Loss Characteristics

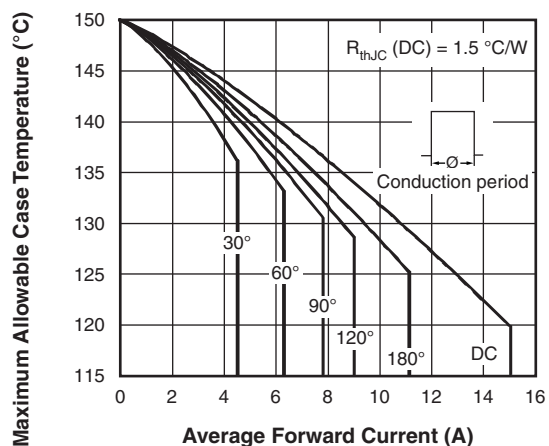


Fig. 2 - Current Rating Characteristics

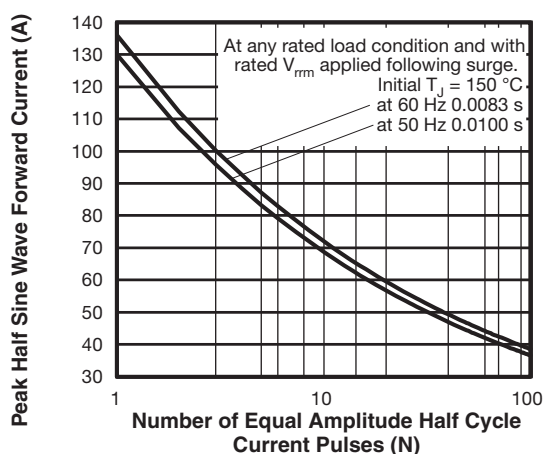


Fig. 5 - Maximum Non-Repetitive Surge Current

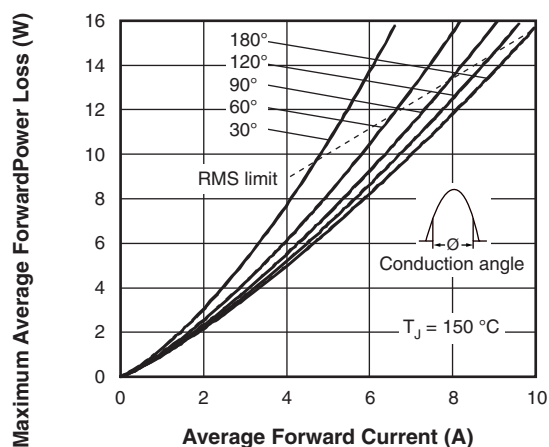


Fig. 3 - Forward Power Loss Characteristics

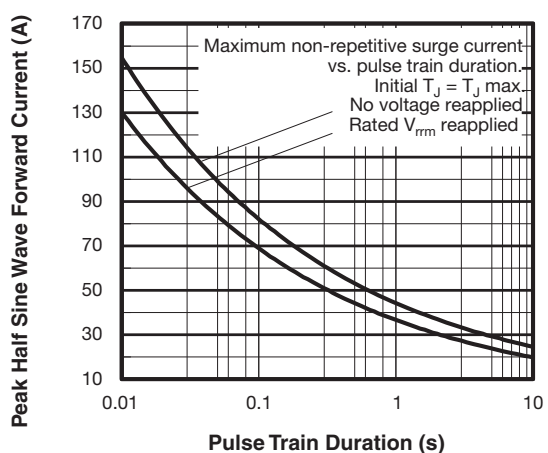


Fig. 6 - Maximum Non-Repetitive Surge Current

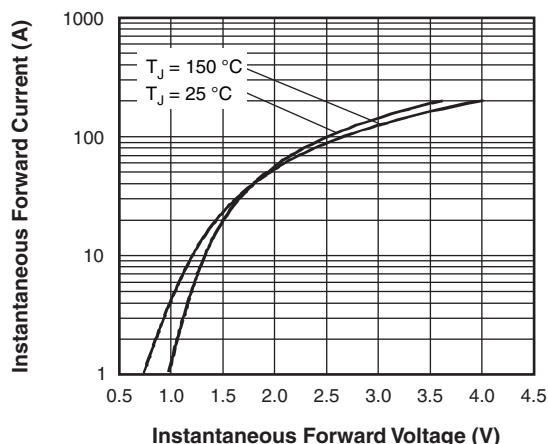


Fig. 7 - Forward Voltage Drop Characteristics

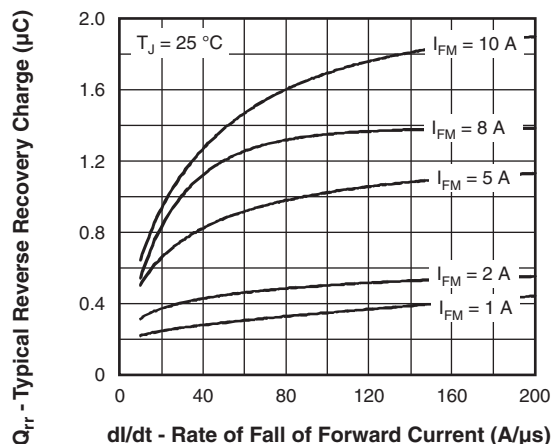


Fig. 10 - Recovery Charge Characteristics, $T_J = 25\text{ }^{\circ}\text{C}$

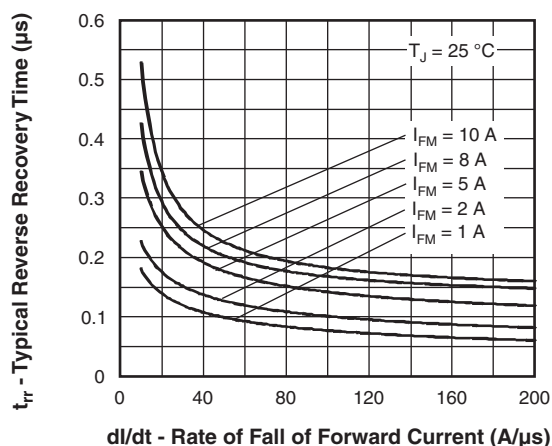


Fig. 8 - Recovery Time Characteristics, $T_J = 25\text{ }^{\circ}\text{C}$

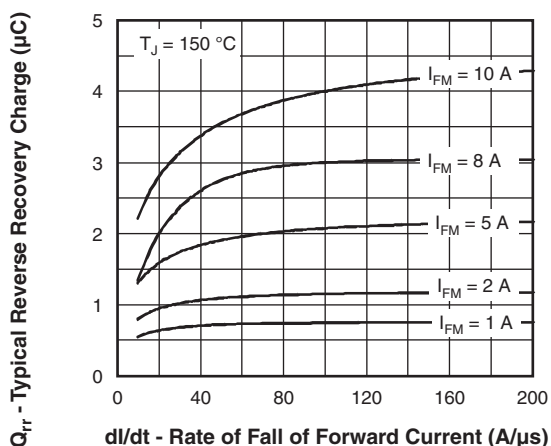


Fig. 11 - Recovery Charge Characteristics, $T_J = 150\text{ }^{\circ}\text{C}$

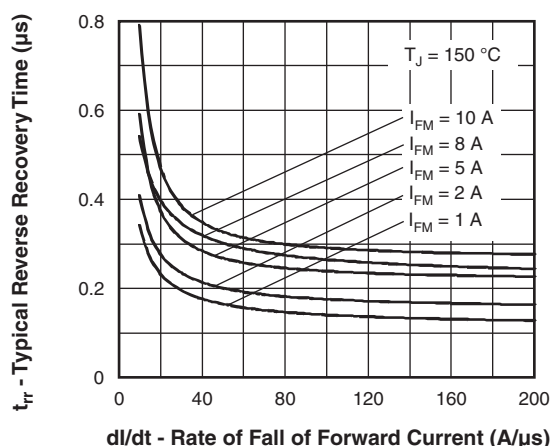


Fig. 9 - Recovery Time Characteristics, $T_J = 150\text{ }^{\circ}\text{C}$

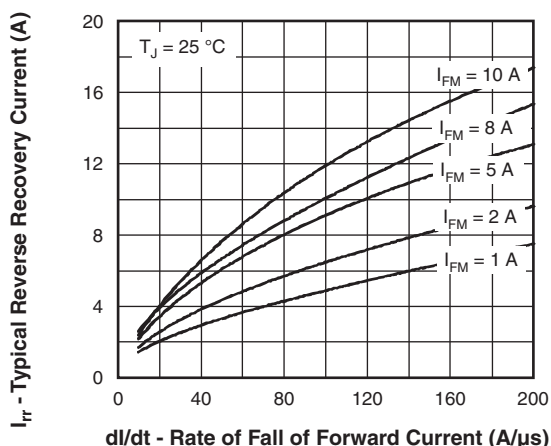


Fig. 12 - Recovery Current Characteristics, $T_J = 25\text{ }^{\circ}\text{C}$

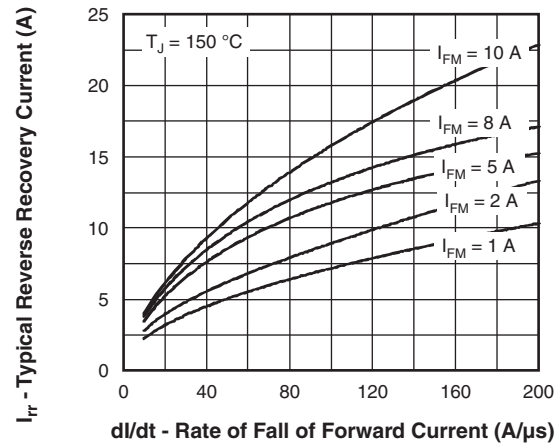


Fig. 13 - Recovery Current Characteristics, $T_J = 150\text{ }^{\circ}\text{C}$

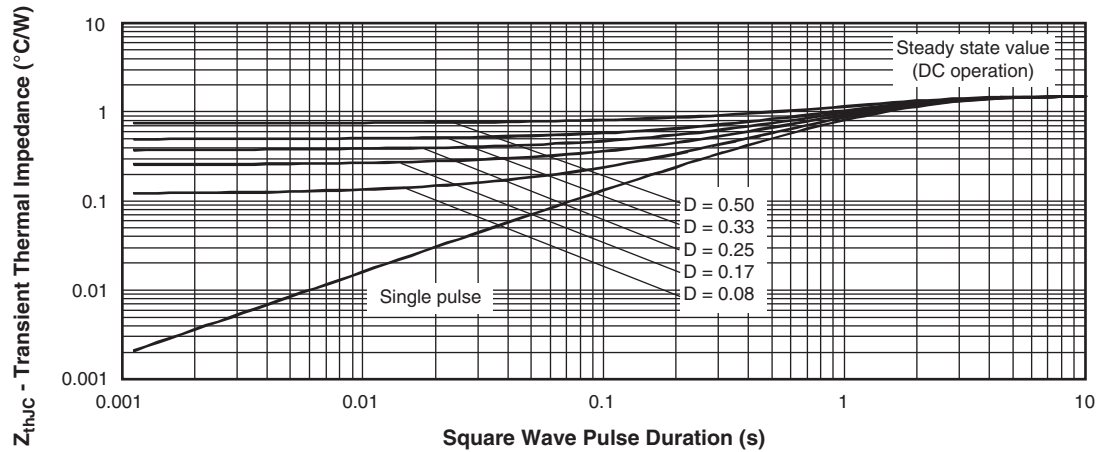


Fig. 14 - Thermal Impedance Z_{thJC} Characteristics

**ORDERING INFORMATION TABLE**

Device code	VS-	10	E	T	F	12	S	L	H	M3
	1	2	3	4	5	6	7	8	9	10

- 1** - Vishay Semiconductors product
- 2** - Current rating (10 = 10 A)
- 3** - Circuit configuration:
E = single
- 4** - Package:
T = D²PAK (TO-263AB)
- 5** - Type of silicon:
F = fast soft recovery rectifier
- 6** - Voltage code x 100 = V_{RRM} — **12 = 1200 V**
- 7** - S = surface mountable
- 8** - L = tape and reel (left oriented), for different orientation, contact factory
- 9** - H = AEC-Q101 qualified
- 10** - Environmental digit:
M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)			
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-10ETF12SLHM3	800	800	13" diameter reel

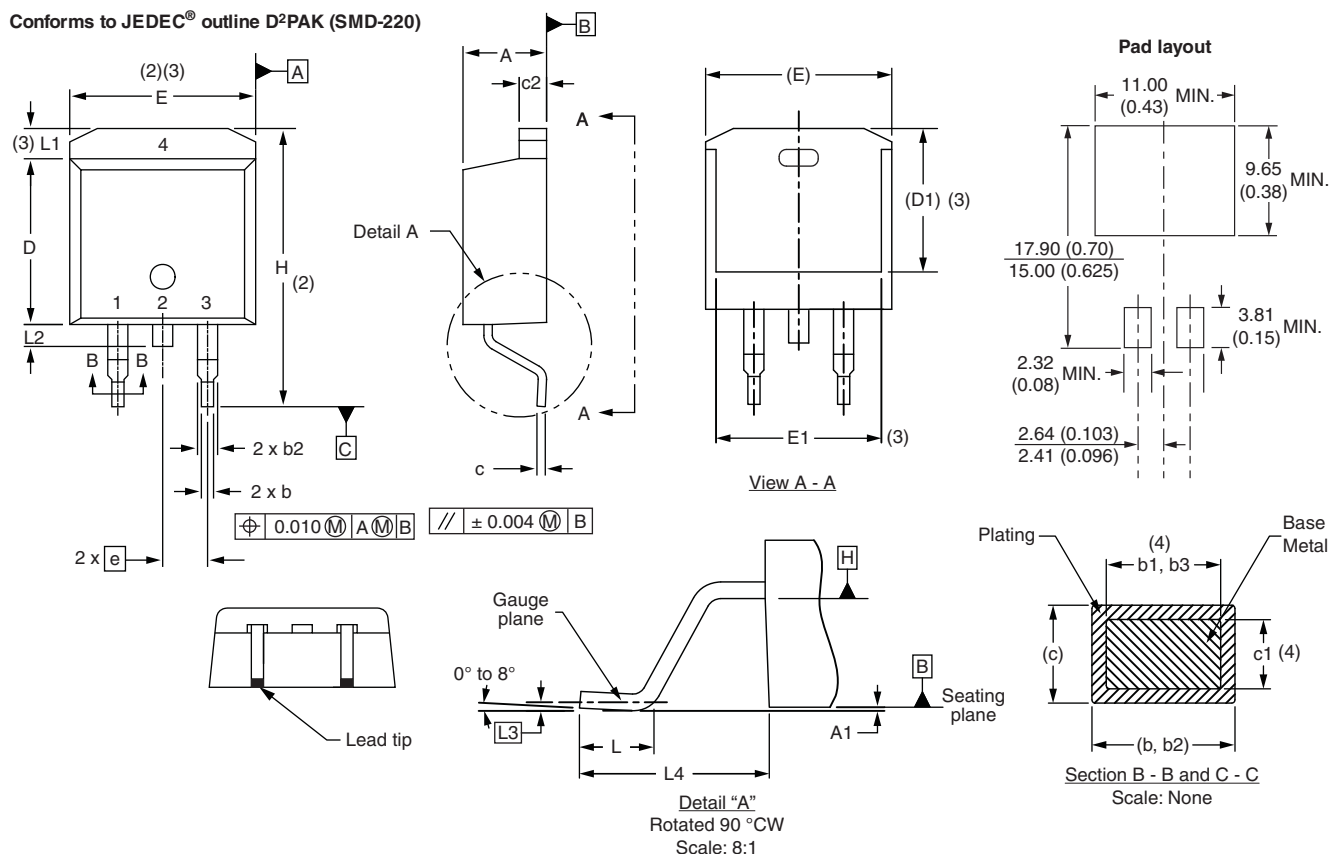
LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95046
Part marking information	www.vishay.com/doc?95444
Packaging information	www.vishay.com/doc?96317



D²PAK

DIMENSIONS in millimeters and inches

Conforms to JEDEC® outline D²PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
H	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010 BSC		
L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB



Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Hyperlinks included in this datasheet may direct users to third-party websites. These links are provided as a convenience and for informational purposes only. Inclusion of these hyperlinks does not constitute an endorsement or an approval by Vishay of any of the products, services or opinions of the corporation, organization or individual associated with the third-party website. Vishay disclaims any and all liability and bears no responsibility for the accuracy, legality or content of the third-party website or for that of subsequent links.

Vishay products are not designed for use in life-saving or life-sustaining applications or any application in which the failure of the Vishay product could result in personal injury or death unless specifically qualified in writing by Vishay. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.